

**TRADEMARK ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT		
<b>NATURE OF CONVEYANCE:</b>	RELEASE BY SECURED PARTY		
<b>CONVEYING PARTY DATA</b>			
<b>Name</b>	<b>Formerly</b>	<b>Execution Date</b>	<b>Entity Type</b>
Venture Lending & Leasing III, Inc.		08/29/2011	CORPORATION: MARYLAND
<b>RECEIVING PARTY DATA</b>			
<b>Name:</b>	Molecular Imprints, Inc.		
<b>Street Address:</b>	1807-C W. Braker Lane		
<b>Internal Address:</b>	Suite 100		
<b>City:</b>	Austin		
<b>State/Country:</b>	TEXAS		
<b>Postal Code:</b>	78758		
<b>Entity Type:</b>	CORPORATION: DELAWARE		
<b>PROPERTY NUMBERS Total: 6</b>			
<b>Property Type</b>	<b>Number</b>	<b>Word Mark</b>	
<b>Serial Number:</b>	76453319	SFIL	
<b>Serial Number:</b>	76453571	S-FIL	
<b>Serial Number:</b>	76453858	SFIL	
<b>Serial Number:</b>	76453866	S-FIL	
<b>Serial Number:</b>	76470850	IMPRIO	
<b>Serial Number:</b>	76470855	IMPRIO	
<b>CORRESPONDENCE DATA</b>			
<b>Fax Number:</b>	(650)493-6811		
	<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
<b>Phone:</b>	6508455968		
<b>Email:</b>	bfriesen@wsgr.com		
<b>Correspondent Name:</b>	Barbara Friesen, c/o WSGR		
<b>Address Line 1:</b>	650 Page Mill Road		
<b>Address Line 2:</b>	FH 2-1-K		
<b>Address Line 4:</b>	Palo Alto, CALIFORNIA 94304		

CH \$165.00 76453319

ATTORNEY DOCKET NUMBER:	29739.032
NAME OF SUBMITTER:	Barbara Friesen
Signature:	/s/ Barbara Friesen
Date:	08/29/2011
Total Attachments: 6 source=Molecular Release#page1.tif source=Molecular Release#page2.tif source=Molecular Release#page3.tif source=Molecular Release#page4.tif source=Molecular Release#page5.tif source=Molecular Release#page6.tif	

**TERMINATION AND RELEASE OF  
INTELLECTUAL PROPERTY SECURITY AGREEMENT**

This Termination and Release of Intellectual Property Security Agreement (the "Agreement"), is made as of August 29, 2011, by VENTURE LENDING & LEASING III, INC., a Maryland corporation ("Secured Party"), in favor of MOLECULAR IMPRINTS, INC., a Delaware corporation (together with its successors and assigns, the "Grantor").

RECITALS

A. Reference is made to that certain Intellectual Property Security Agreement dated as of October 1, 2002, as supplemented by that certain Supplement No. 1 to Intellectual Property Security Agreement dated as of January 31, 2003 (collectively, the "Loan Agreement"), by and between Grantor and Secured Party, whereby Grantor granted to Secured Party a security interest in Grantor's entire right, title and interest in all Intellectual Property of the Grantor (the "Collateral").

B. A Grant of Security Interest in Intellectual Property was filed with the United States Patent and Trademark Office, Patent Division, on February 19, 2003, at Reel/Frame 013760/0150 to evidence the security interest in patents and patent applications granted under the Loan Agreement.

C. A Grant of Security Interest in Intellectual Property was filed with the United States Patent and Trademark Office, Trademark Division, on February 19, 2003, at Reel/Frame 2674/0970 to evidence the security interest in trademarks and trademark applications granted under the Loan Agreement.

D. Debtor has provided cash collateral for its Obligations under the Loan Agreement and as a result, Grantor has requested, and Secured Party has agreed, to release its security interest in the Collateral.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Secured Party agrees as follows:

1. Secured Party hereby expressly confirms the termination and release to Grantor of its security interest in and to all Collateral, including, but not limited to:

(a) All letters patent of, or rights corresponding thereto in, the United States or any other country, all registrations and recordings thereof, and all applications for letters patent of, or rights corresponding thereto in the United States or any other country, including, without limitation, registrations, recordings and applications in the United States Patent and Trademark Office or in any similar office or agency of the United States, any State thereof or any other country; all reissues, continuations, continuations-in-part or extensions thereof; all petty patents, divisionals, and patents of addition; and all patents to be issued under any such applications, including without limitation each patent and patent application set forth on Exhibit A attached hereto (collectively, the "Patents");

(b) All trademarks, trade names, corporate names, business names, trade styles, service marks, logos, other source or business identifiers, prints and labels on which any of the foregoing have appeared or appear, designs and general intangibles of like nature, all registrations and recordings thereof, and any applications in connection therewith, including, without limitation, registrations, recordings and applications in the United States Patent and Trademark Office or in any similar office or agency of the United States, any State thereof or any other country or political subdivision thereof, and reissues, extensions or renewals thereof and the entire goodwill of the business of Grantor connected with and

symbolized by such trademarks, including without limitation each trademark and trademark application set forth on Exhibit B attached hereto (collectively, the "Trademarks").

[Signature Page Follows]

IN WITNESS WHEREOF, Secured Party has executed and delivered this Termination and Release as of the day and year first above written..

**VENTURE LENDING & LEASING III, INC.**


By:   
Name: JAY Cohan  
Title: Vice President

Exhibit A

Patents

<u>Description</u>	<u>Registration/Serial Number</u>	<u>Registration/Application Date</u>
Methods of Manufacturing a Lithography Template	10/136,188	05/01/2002
Method and Apparatus for Whole Wafer Planarization Using Optical Flats and Light Curable Liquids	60/394,458	07/08/2002
System and Method for Dispensing Liquids	10/191,749	07/09/2002
Formation of Discontinuous Films During an Imprint Lithography Process	10/194,411	07/11/2002
Step and Repeat Imprint Lithography Process	10/194,991	07/11/2002
Step and Repeat Imprint Lithography Systems	10/194,414	07/11/2002
Method and System for Fabricating Nanoscale Patterns Using an Electric Field	10/194,410	07/11/2002
Scatterometry Alignment for Imprint Lithography	10/210,785	08/01/2002
Alignment Systems for Imprint Lithography	10/210,894	08/01/2002
Alignment Methods for Imprint Lithography	10/210,780	08/01/2002
A Method of Forming a Layer on a Substrate to Facilitate Fabrication of Metrology Standards	10/264,926	10/04/2002
Functional Patterning Material for Imprint Lithography Processes	10/235,314	09/05/2002
Method and System for Determining	10/318,365	12/12/2002

**Characteristics of Substrates Employing  
Fluid Geometries**

<b>Method of Reducing Pattern Distortions During Imprint Lithography Processes</b>	10/293,223	11/13/2002
<b>A Method and a Mold to Arrange Features on a Substrate to Replicate Features Having Minimal Dimensional Variability</b>	10/264,960	10/04/2002
<b>Mass Production of Photonic Crystals and Optical Components</b>	preparing for filing	
<b>A Chucking System for Modulating Shapes of Substrates</b>	10/293,224	11/13/2002
<b>A Method for Modulating Shapes of Substrates</b>	not assigned	12/11/2002
<b>Methods of Inspecting a Lithography Template</b>	10/293,919	11/13/2002
<b>Method and System for Magnification and Distortion Control for Layer-to-Layer Alignment in Imprint Lithography</b>	60/432,584	12/11/2002
<b>Surface Activation Monomer</b>	preparing for filing	
<b>Method and System for Magnification and Distortion Control for Layer-to-Layer Alignment in Imprint Lithography</b>	60/433,477	12/13/2002
<b>Method for Fabricating Bulbous-Shaped Vias</b>	10/227,105	08/23/2002

Exhibit B

Trademarks

<u>Description</u>	<u>Registration/Serial Number</u>	<u>Registration/Application Date</u>
S-FIL	76/453,571	09/27/2002
SFIL	76/453,319	09/26/2002
S-FIL	76/453,866	09/30/2002
SFIL	76/453,858	09/30/2002
IMPRIO	76/470,850	11/29/2002
IMPRIO	76/470,855	11/29/2002